Common Mode Transient Immunity at Low Level Output	$\|CM_L\|$	I_F=0mA V_{CC}=30V, T_a=25 , V_O(max)=1V V_{CM}=1000Vpp	±35	-	-	kV/μs

All Typical values at T_a=25

: Input signal (f=25kHz,duty=50%, tr=tf=5ns or less). C_L is less than 15 pF which includes probe and stray wiring capacitance.

: CM_H is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state (VO 26V).

: CML is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state (VO 1V).

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	$I_{F(ON)}$	6.5	-	10	mA
Input Off-state Voltage	$V_{F(OFF)}$	0	-	0.8	V
Supply Voltage	V_{CC}	15	-	30	V
Operating Frequency	f	-	-	25	kHz

: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

: Aceramic capacitor(0.1μF) should be connected between pin 6 (V_{CC}) and pin 4 (GND) to stabilize the operation of a high-i ð y biln Ő ; e ʒ ed i Ł = b ˜ Y ş

	JOC : Company Abbr. 341 : Part Number VYAWW : LOT NO.
JOC – Company Abbr. 341 – Part Number Y – Lead Form Option Z – Tape and Reel Option (T1/T2) G – Green V – VDE Option (V or None)	
T1/T2	3000 Units/Reel

FIG.1: Forward Current vs. Forward Voltage

FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

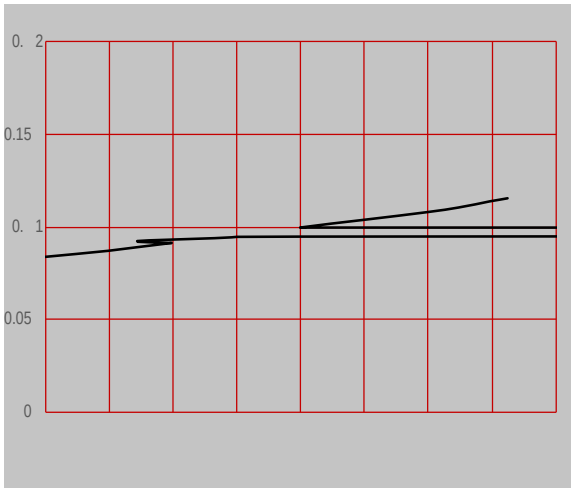

0. 2
0.15
0. 1
0.05
0

FIG.13: Propagation Delay Time vs. Supply Voltage

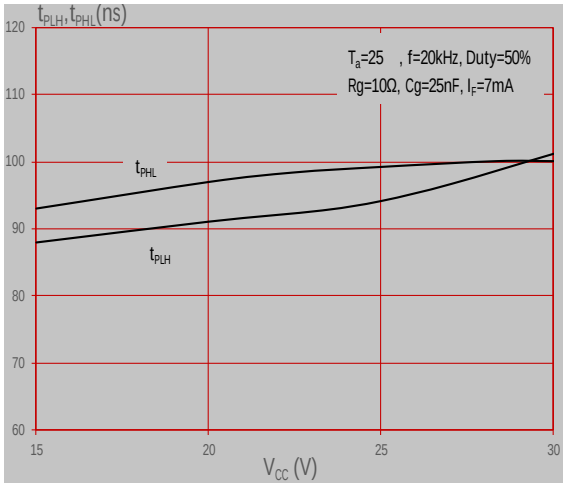
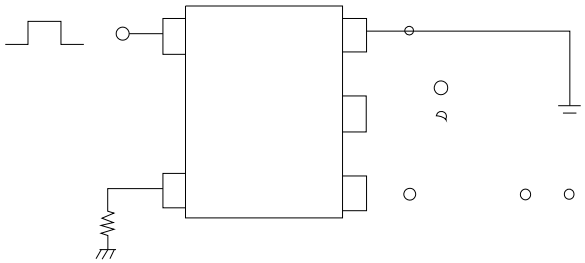
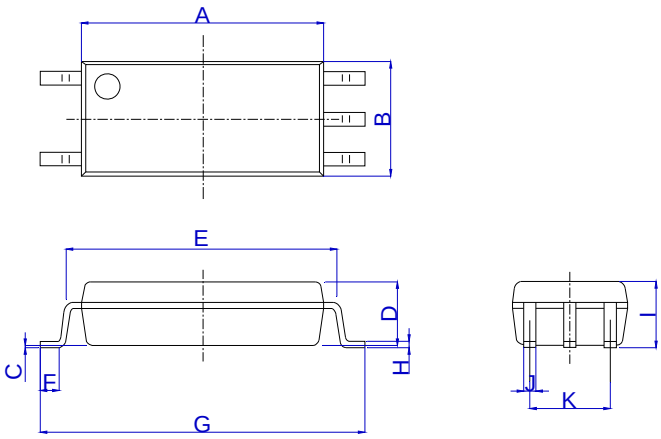
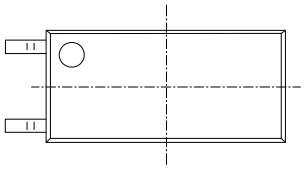


FIG.14: Switching Time Test Circuit and Waveform

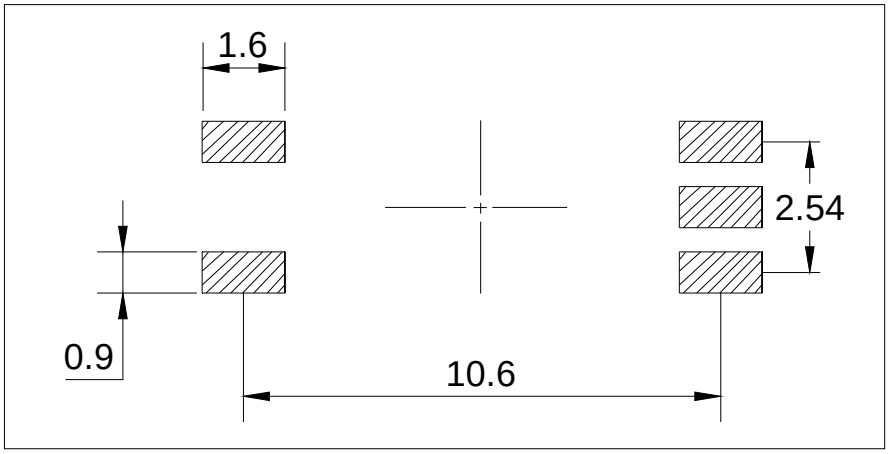


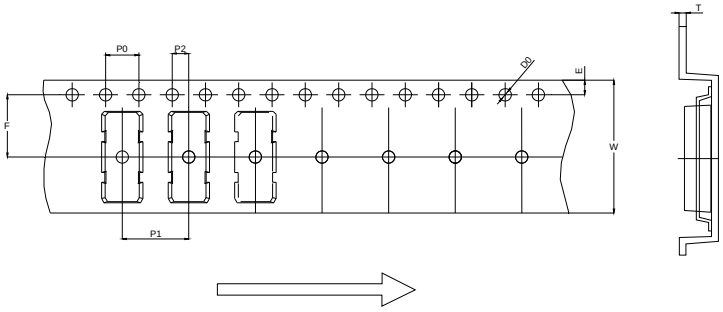


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K	2.29		2.79	0.090		0.110

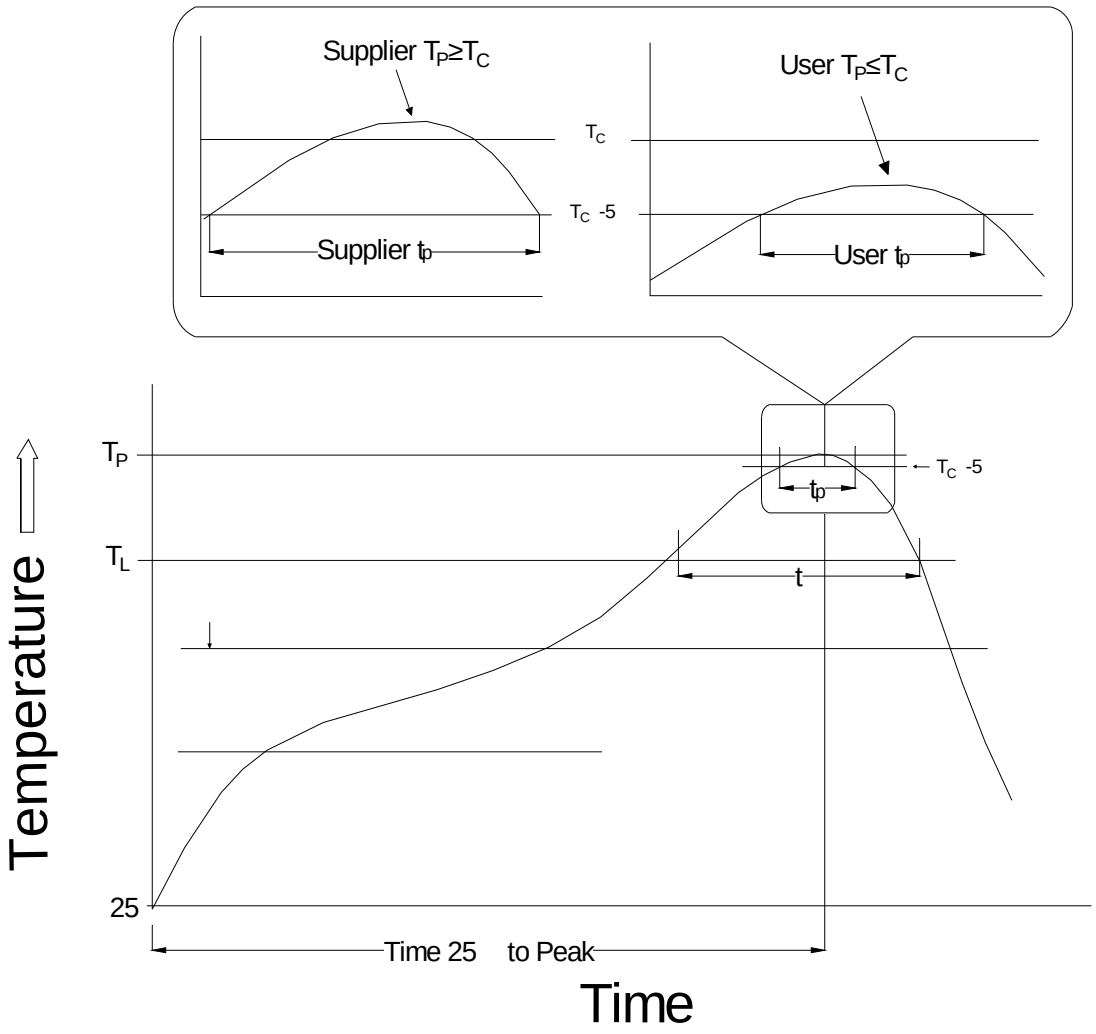


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.55		1.15	0.022		0.045
G	10.78		11.38	0.424		0.448
H	0.06		0.26	0.002		0.010
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						


1.6
2.54
0.9
10.6



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.50	1.55	1.60	0.059	0.061	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.80	16.00	16.20	0.622	0.630	0.638


Supplier $T_P \geq T_C$
User $T_P \leq T_C$
T_C
T_C -5
Supplier t_p
User t_p
T_P
T_L
25
T_C -5
t_p
t
Temperature
Time 25 to Peak
Time

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum